IPC ASSOCIATION CONNECT ELECTRONICS INDUSTR	© Copyright 2005. II	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			der both Thi	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.								
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Typhttp://www.ipc.org/IPC-175x Distribute				* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi				ials and Mfg Information				
upplier Infor	mation								,					
Company name*			Company unique ID			U	Unique ID Authority				Response Date*			
nsemi											2025-06-04			
ontact Name			Title - Contact			Pl	Phone - Contact*				Email - Contact*			
Product-Env-Ste	wards		Product Enviro Compliance			N	NA				Product-Env-Stewards@onsemi.com			
uthorized Repre	esentative*	Title - Representative			Pl	Phone - Representative*				Email - Representative*				
Product-Env-Ste	wards	Product Enviro Compliance			N	NA				Product-Env-Stewards@onsemi.com				
Reque	ster Item Number	Mfr Item	Number	Mfr Item Name		I	Effective Date	Version	n Manufacturing Site			Weight*	UOM	Unit Type
	MBR10100MFST3G 10 A		10 A, 100 V Schottky Diode in SO-8FL		BFL 2	2025-06-04 MY1		Y1	113.069		mg	Each		
	g Process Informat		arminal Reso	Alloy	STD-020 MSL Ra	oting	Dank Droom	e Rody Tamp	aratura	May Time at Pools	Tamparet	ura Numbe	er of Reflow Cyc	olac
		Terminal Base Alloy J-ST CU Alloy 1		STD-020 MSL Ka	atting	Peak Process Body Tempera 260 C		erature	ture Max Time at Peak Tempera 30 seco			of Kellow Cyc	cies	
•	Tili (Sii) - aimealeu		O Alloy	1			200	C		30	secon	us  3		
omments	n time at peak temperatu	no dunina sal	domina is 10-2	A seconds										
	n time at peak temperatu ation regarding material													

RoHS Material Composition Declaration			Declaration Type *	Detailed						
irective 2015/863/EU amending RoHS irective 2011/65/EU  RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledges and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies of Supplier's Standard Terms andConditions of Sale applicable to such part shall apply.										
RoHS Declaration * 4 - Item(s	) does not contain RoHS restricted substance	s per the definition above except for selected exemp	tions Supplier Acceptance	* Accepted						
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.										
Supplier Digital Signature Ra	astislav Drska	-En								

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Clip	4.8	mg	Supplier	Zinc (Zn)	7440-66-6		0.0058	mg
			Supplier	Iron (Fe)	7439-89-6		0.1128	mg
			Supplier	Copper (Cu)	7440-50-8		4.68	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0014	mg
Die	0.713	mg	Supplier	Silicon (Si)	7440-21-3		0.713	mg
Die Attach Solder	11.9	mg	Supplier	Silver (Ag)	7440-22-4		0.2975	mg
			A	Lead (Pb)	7439-92-1	7a	11.0075	mg
			Supplier	Tin (Sn)	7440-31-5		0.595	mg
Lead Frame	47.57	mg	Supplier	Silver (Ag)	7440-22-4		0.0285	mg
			Supplier	Iron (Fe)	7439-89-6		0.0476	mg
			Supplier	Copper (Cu)	7440-50-8		47.4796	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0143	mg
Mold Compound-Black	47.136	mg		Epoxy resin	proprietary data		3.5352	mg
			Supplier	Phenolic Resin	Proprietary Data		1.1784	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		3.5352	mg
			Supplier	Carbon Black (C)	1333-86-4		0.2357	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		38.6515	mg
Plating	0.95	mg	Supplier	Tin (Sn)	7440-31-5		0.95	mg